NEC

MOS INTEGRATED CIRCUIT

μPD42S16805L, 4216805L

3.3 V OPERATION 16 M-BIT DYNAMIC RAM 2 M-WORD BY 8-BIT, HYPER PAGE MODE

Description

The μPD42S16805L, 4216805L are 2 097 152 words by 8 bits dynamic CMOS RAMs with optional hyper page mode.

Hyper page mode is a kind of the page mode and is useful for the read operation.

The μPD42S16805L, 4216805L are packed in 28-pin plastic TSOP(II) and 28-pin plastic SOJ.

Features

- Hyper page mode
- Single +3.3 V±0.3 V power supply
- 2 097 152 words by 8 bits organization

Part number	Access time (MAX.)	R/W cycle time (MIN.)	Hyper page mode cycle time (MIN.)
μPD42S16805L-A60, 4216805L-A60	60 ns	104 ns	25 ns
μPD42S16805L-A70, 4216805L-A70	70 ns	124 ns	30 ns

- μPD42S16805L can execute $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh

Part number	Refresh cycle	Refresh
μPD42S16805L	4 096 cycles/128 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh
μPD4216805L	4 096 cycles/64 ms	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh $\overline{\text{RAS}}$ only refresh Hidden refresh

Ordering Information

Part number	Access time (MAX.)	Package	Refresh
μPD42S16805LG5-A60	60 ns	28-pin Plastic TSOP(II) (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ self refresh $\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD42S16805LG5-A70	70 ns		
~~μPD42S16805LG5-A60-7KD~~	~~60 ns~~	~~28-pin Plastic TSOP (II) (400 mil) Reverse bent~~	
~~μPD42S16805LG5-A70-7KD~~	~~70 ns~~		
μPD42S16805LLE-A60	60 ns	28-pin Plastic SOJ (400 mil)	
μPD42S16805LLE-A70	70 ns		
μPD4216805LG5-A60	60 ns	28-pin Plastic TSOP (II) (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD4216805LG5-A70	70 ns		
~~μPD4216805LG5-A60-7KD~~	~~60 ns~~	~~28-pin Plastic TSOP (II) (400 mil) Reverse bent~~	
~~μPD4216805LG5-A70-7KD~~	~~70 ns~~		
μPD4216805LLE-A60	60 ns	28-pin Plastic SOJ (400 mil)	
μPD4216805LLE-A70	70 ns		

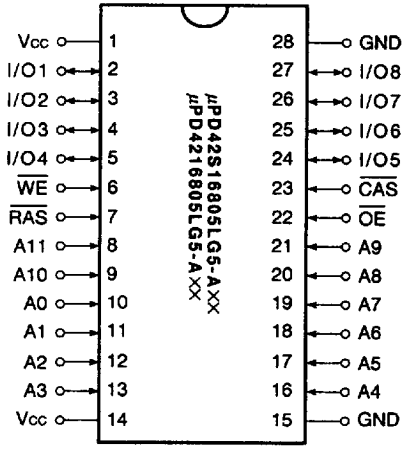
Quality Grade

Standard

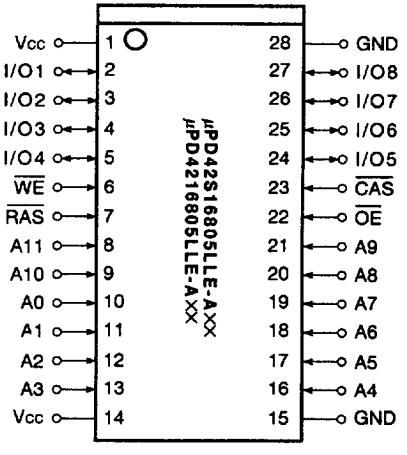
Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

Pin Configurations (Marking side)

28-pin Plastic TSOP (II) (400 mil)

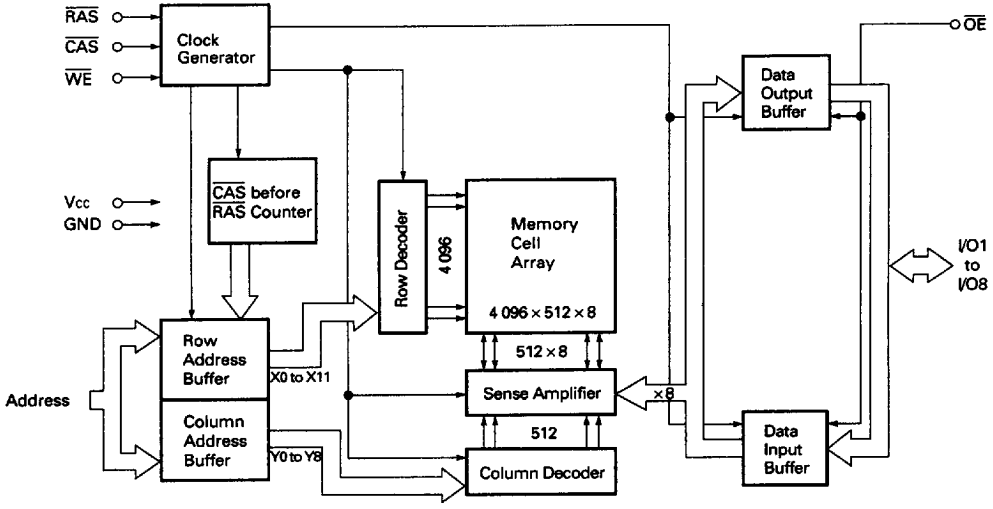


28-pin Plastic SOJ (400 mil)



A0 to A11	: Address Inputs
I/O1 to I/O8	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Power Supply
GND	: Ground

Block Diagram



Input/Output Pin Functions

The μPD42S16805L, 4216805L have input pins $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$, A0 to A11 and input/output pins I/O1 to I/O8.

Pin name	Input/ Output	Function
$\overline{RAS}$ (Row address strobe)	Input	$\overline{RAS}$ activates the sense amplifier by latching a row address and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address. It also selects the following function. • $\overline{CAS}$ before $\overline{RAS}$ refresh
$\overline{CAS}$ (Column address strobe)		$\overline{CAS}$ activates data input/output circuit by latching column address and selecting a digit line connected with the sense amplifier.
A0 to A11 (Address inputs)		Address bus. Input total 21-bit of address signal, upper 12-bit and lower 9-bit in sequence (address multiplex method). Therefore, one word is selected from 2 097 152-word by 8-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{RAS}$. Then, switch the address bus to column address and activate $\overline{CAS}$. Each address is taken into the device when $\overline{RAS}$ and $\overline{CAS}$ are activated. Therefore, the address input setup time (t_{ASR}, t_{ASC}) and hold time (t_{RAH}, t_{CAH}) are specified for the activation of $\overline{RAS}$ and $\overline{CAS}$.
$\overline{WE}$ (Write enable)		Write control signal. Write operation is executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{WE}$.
$\overline{OE}$ (Output enable)		Read control signal. Read operation can be executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{OE}$. If $\overline{WE}$ is activated during read operation, $\overline{OE}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O8 (Data inputs/outputs)	Input/ Output	8-bit data bus. I/O1 to I/O8 are used to input/output data.

Hyper Page Mode

The hyper page mode is a kind of page mode with enhanced features. The two major features of the hyper page mode are as follows.

1. Data output time is extended.

   In the hyper page mode, the output data is held to the next $\overline{CAS}$ cycle's falling edge, instead of the rising edge. For this reason, valid data output time in the hyper page mode is extended compared with the fast page mode (=data extend function). In the fast page mode, the data output time becomes shorter as the $\overline{CAS}$ cycle time becomes shorter. Therefore, in the hyper page mode, the timing margin in read cycle is larger than that of the fast page mode even if the $\overline{CAS}$ cycle time becomes shorter.

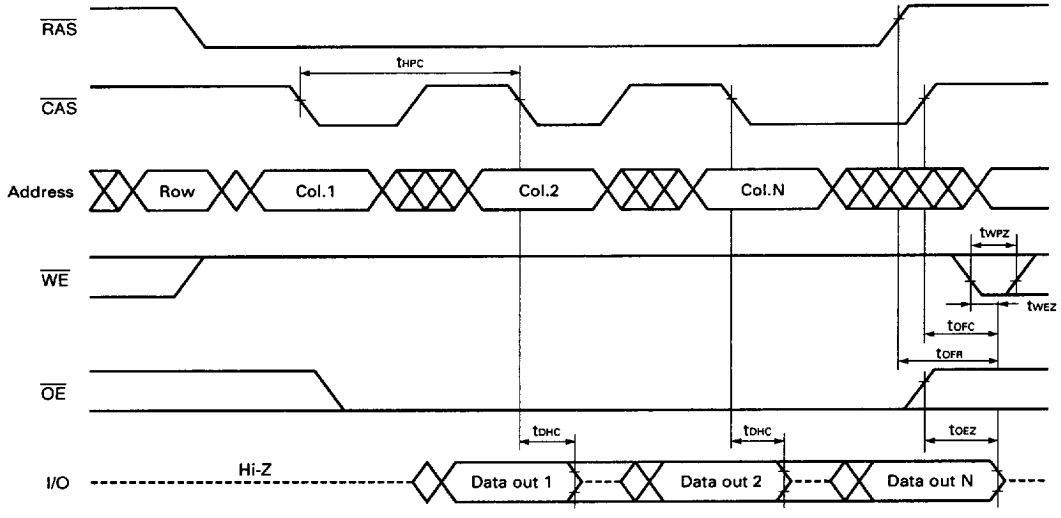
2. The $\overline{CAS}$ cycle time in the hyper page mode is shorter than that in the fast page mode.

In the hyper page mode, due to the data extend function, the $\overline{CAS}$ cycle time can be shorter than in the fast page mode if the timing margin is the same.

Taking a device whose t_{RAC} is 60 ns as an example, the $\overline{CAS}$ cycle time in the hyper page mode is 25 ns while that in the fast page mode is 40 ns.

In the hyper page mode, read (data out) and write (data in) cycles can be executed repeatedly during one $\overline{RAS}$ cycle. The hyper page mode allows both read and write operations during one cycle, but the performance is equivalent to that of the fast page mode in that case.

Hyper Page Mode Read Cycle



To make I/Os to Hi-Z in read cycle, it is necessary to control $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$ as follows. The effective specification depends on the state of each signal.

(1) $\overline{RAS}$, $\overline{CAS}$: inactive (at the end of read cycle)
$\overline{WE}$: inactive, $\overline{OE}$: active
t_{OFC} is effective when $\overline{RAS}$ is inactivated before $\overline{CAS}$ is inactivated.
t_{OFR} is effective when $\overline{CAS}$ is inactivated before $\overline{RAS}$ is inactivated.

(2) Both $\overline{RAS}$ and $\overline{CAS}$ are active or either $\overline{RAS}$ or $\overline{CAS}$ is active (in read cycle)
$\overline{WE}$: active, $\overline{OE}$: active···t_{WEZ}, t_{WPZ} are effective.
$\overline{WE}$: inactive, $\overline{OE}$: inactive···t_{OEZ} is effective.

Electrical Specifications

- All voltages are referenced to GND.
- After power up, wait more than 100 μs and then, execute eight $\overline{CAS}$ before $\overline{RAS}$ or $\overline{RAS}$ only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on Any Pin Relative to GND	V_T		−0.5 to +4.6	V
Supply Voltage	V_{CC}		−0.5 to +4.6	V
Output Current	I_O		20	mA
Power Dissipation	P_D		1	W
Operating Temperature	T_{opt}		0 to +70	°C
Storage Temperature	T_{stg}		−55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply Voltage	V_{CC}		3.0	3.3	3.6	V
High Level Input Voltage	V_{IH}		2.0		V_{CC} +0.3	V
Low Level Input Voltage	V_{IL}		−0.3		+0.8	V
Ambient Temperature	T_a		0		70	°C

Capacitance (T_a = 25 °C, f = 1 MHz)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input Capacitance	C_{I1}	Address			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	pF
Data Input/Output Capacitance	$C_{I/O}$	I/O			7	pF

DC Characteristics (Recommended Operating Conditions unless otherwise noted)

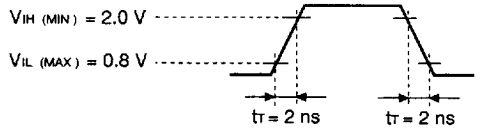
Parameter		Symbol	Test condition		MIN.	MAX.	Unit	Notes
Operating current		I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ Cycling $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 60 ns		80	mA	1,2,3
				t_{RAC} = 70 ns		70		
Standby current	μPD42S16805L	I_{CC2}	$\overline{RAS}$, $\overline{CAS} \geqq V_{IH (MIN.)}$, I_O = 0 mA			0.5	mA	
			$\overline{RAS}$, $\overline{CAS} \geqq V_{CC}$ – 0.2 V, I_O = 0 mA			0.15		
	μPD4216805L		$\overline{RAS}$, $\overline{CAS} \geqq V_{IH (MIN.)}$, I_O = 0 mA			2		
			$\overline{RAS}$, $\overline{CAS} \geqq V_{CC}$ – 0.2 V, I_O = 0 mA			0.5		
$\overline{RAS}$ only refresh current		I_{CC3}	$\overline{RAS}$ Cycling $\overline{CAS} \geqq V_{IH (MIN.)}$ $t_{RC} = t_{RC (MIN.)}$ I_O = 0 mA	t_{RAC} = 60 ns		80	mA	1,2,3,4
				t_{RAC} = 70 ns		70		
Operating current (Hyper page mode)		I_{CC4}	$\overline{RAS} \leqq V_{IL (MAX.)}$ $\overline{CAS}$ Cycling $t_{HPC} = t_{HPC (MIN.)}$ I_O = 0 mA	t_{RAC} = 60 ns		90	mA	1,2,5
				t_{RAC} = 70 ns		80		
$\overline{CAS}$ before $\overline{RAS}$ refresh current		I_{CC5}	$\overline{RAS}$ Cycling $t_{RC} = t_{RC (MIN.)}$ I_O = 0 mA	t_{RAC} = 60 ns		80	mA	1,2
				t_{RAC} = 70 ns		70		
$\overline{CAS}$ before $\overline{RAS}$ long refresh current (4 096 Cycles / 128 ms, only for the μPD42S16805L)		I_{CC6}	$\overline{CAS}$ before $\overline{RAS}$ refresh: 4 096 Cycles / 128 ms $\overline{RAS}$, $\overline{CAS}$: V_{CC}–0.2 V $\leqq V_{IH} \leqq V_{IH (MAX.)}$ 0 V $\leqq V_{IL} \leqq$ 0.2 V Standby : $\overline{RAS} \geqq V_{CC}$–0.2 V Address : V_{IH} or V_{IL} $\overline{WE}$, $\overline{OE}$: V_{IH} I_O = 0 mA	$t_{RAS} \leqq$ 1 μs		220	μA	1,2
Self refresh current ($\overline{CAS}$ before $\overline{RAS}$ self refresh, only for the μPD42S16805L)		I_{CC7}	$\overline{RAS}$, $\overline{CAS}$: V_{CC}–0.2 V $\leqq V_{IH} \leqq V_{IH (MAX.)}$ 0 V $\leqq V_{IL} \leqq$ 0.2 V I_O = 0 mA			150	μA	2
Input leakage current		$I_{I (L)}$	V_I = 0 to 3.6 V all other pins not under test = 0 V		–5	+5	μA	
Output leakage current		$I_{O (L)}$	V_O = 0 to 3.6 V Output is disabled (Hi-Z)		–5	+5	μA	
High level output voltage		V_{OH}	I_O = –2.0 mA		2.4		V	
Low level output voltage		V_{OL}	I_O = +2.0 mA			0.4	V	

Notes 1. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5} and I_{CC6} depend on cycle rates (t_{RC} and t_{HPC}).
2. Specified values are obtained with outputs unloaded.
3. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during $\overline{RAS} \leqq V_{IL(MAX.)}$ and $\overline{CAS} \geqq V_{IH(MIN.)}$.
4. I_{CC3} is measured assuming that all column address inputs are held at either high or low.
5. I_{CC4} is measured assuming that all column address inputs are switched only once during each hyper page cycle.

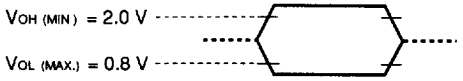
AC Characteristics (Recommended Operating Conditions unless otherwise noted)

AC Characteristics Test Conditions

(1) Input timing specification



(2) Output timing specification



(3) Loading conditions are 100 pF + 1 TTL.

Common to Read, Write, Read Modify Write Cycle

Parameter		Symbol	tRAC = 60 ns		tRAC = 70 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.		
Read / Write Cycle Time		tRC	104	–	124	–	ns	
$\overline{RAS}$ Precharge Time		tRP	40	–	50	–	ns	
$\overline{CAS}$ Precharge Time		tCPN	10	–	10	–	ns	
$\overline{RAS}$ Pulse Width		tRAS	60	10 000	70	10 000	ns	
$\overline{CAS}$ Pulse Width		tCAS	10	10 000	12	10 000	ns	
$\overline{RAS}$ Hold Time		tRSH	10	–	12	–	ns	
$\overline{CAS}$ Hold Time		tCSH	40	–	50	–	ns	
$\overline{RAS}$ to $\overline{CAS}$ Delay Time		tRCD	14	45	14	52	ns	1
$\overline{RAS}$ to Column Address Delay Time		tRAD	12	30	12	35	ns	1
$\overline{CAS}$ to $\overline{RAS}$ Precharge Time		tCRP	5	–	5	–	ns	2
Row Address Setup Time		tASR	0	–	0	–	ns	
Row Address Hold Time		tRAH	10	–	10	–	ns	
Column Address Setup Time		tASC	0	–	0	–	ns	
Column Address Hold Time		tCAH	10	–	12	–	ns	
$\overline{OE}$ Lead Time Referenced to $\overline{RAS}$		tOES	0	–	0	–	ns	
$\overline{CAS}$ to Data Setup Time		tCLZ	0	–	0	–	ns	
$\overline{OE}$ to Data Setup Time		tOLZ	0	–	0	–	ns	
$\overline{OE}$ to Data Delay Time		tOED	13	–	15	–	ns	
Transition Time (Rise and Fall)		tT	1	50	1	50	ns	
Refresh Time	μPD42S16805L	tREF	–	128	–	128	ms	3
	μPD4216805L		–	64	–	64	ms	

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{RAS}$
$t_{RAD} \leqq t_{RAD\ (MAX)}$ and $t_{RCD} \leqq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leqq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD(MAX.)}$ and $t_{RCD(MAX.)}$ are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geqq t_{RAD(MAX.)}$ and $t_{RCD} \geqq t_{RCD(MAX.)}$ will not cause any operation problems.

2. $t_{CRP(MIN.)}$ requirement is applied to $\overline{RAS}$, $\overline{CAS}$ cycles.
3. This specification is applied only to the μPD42S16805L.

Read Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
Access Time from $\overline{RAS}$	t_{RAC}	–	60	–	70	ns	1
Access Time from $\overline{CAS}$	t_{CAC}	–	15	–	18	ns	1
Access Time from Column Address	t_{AA}	–	30	–	35	ns	1
Access Time from $\overline{OE}$	t_{OEA}	–	15	–	18	ns	
Column Address Lead Time Referenced to $\overline{RAS}$	t_{RAL}	30	–	35	–	ns	
Read Command Setup Time	t_{RCS}	0	–	0	–	ns	
Read Command Hold Time Referenced to $\overline{RAS}$	t_{RRH}	0	–	0	–	ns	2
Read Command Hold Time Referenced to $\overline{CAS}$	t_{RCH}	0	–	0	–	ns	2
Output Buffer Turn-off Delay Time from $\overline{OE}$	t_{OEZ}	0	13	0	15	ns	3

Notes 1. For read cycles, access time is defined as follows:

Input Conditions	Access Time	Access Time from $\overline{RAS}$
$t_{RAD} \leqq t_{RAD\ (MAX.)}$ and $t_{RCD} \leqq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leqq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD(MAX.)}$ and $t_{RCD(MAX.)}$ are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geqq t_{RAD(MAX.)}$ and $t_{RCD} \geqq t_{RCD(MAX.)}$ will not cause any operation problems.

2. Either $t_{RCH(MIN.)}$ or $t_{RRH(MIN.)}$ should be met in read cycles.
3. $t_{OEZ(MAX.)}$ defines the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL}.

Write Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
$\overline{WE}$ Hold Time Referenced to $\overline{CAS}$	t_{WCH}	10	–	10	–	ns	1
$\overline{WE}$ Pulse Width	t_{WP}	10	–	10	–	ns	1
$\overline{WE}$ Lead Time Referenced to $\overline{RAS}$	t_{RWL}	10	–	12	–	ns	
$\overline{WE}$ Lead Time Referenced to $\overline{CAS}$	t_{CWL}	10	–	12	–	ns	
$\overline{WE}$ Setup Time	t_{WCS}	0	–	0	–	ns	2
$\overline{OE}$ Hold Time	t_{OEH}	0	–	0	–	ns	
Data-in Setup Time	t_{DS}	0	–	0	–	ns	3
Data-in Hold Time	t_{DH}	10	–	10	–	ns	3

Notes 1. $t_{WP(MIN.)}$ is applied to late write cycles or read modify write cycles. In early write cycles, $t_{WCH(MIN.)}$ should be met.

2. If $t_{WCS} \geqq t_{WCS(MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.

3. $t_{DS(MIN.)}$ and $t_{DH(MIN.)}$ are referenced to the $\overline{CAS}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{WE}$ falling edge.

Read Modify Write Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
Read Modify Write Cycle Time	t_{RWC}	133	–	157	–	ns	
$\overline{RAS}$ to $\overline{WE}$ Delay Time	t_{RWD}	77	–	89	–	ns	1
$\overline{CAS}$ to $\overline{WE}$ Delay Time	t_{CWD}	32	–	37	–	ns	1
Column Address to $\overline{WE}$ Delay Time	t_{AWD}	47	–	54	–	ns	1

Note 1. If $t_{WCS} \geqq t_{WCS(MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geqq t_{RWD(MIN.)}$, $t_{CWD} \geqq t_{CWD(MIN.)}$, $t_{AWD} \geqq t_{AWD(MIN.)}$, and $t_{CPWD} \geqq t_{CPWD(MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Hyper Page Mode

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.		
Read / Write Cycle Time	t_{HPC}	25	–	30	–	ns	
$\overline{RAS}$ Pulse Width	t_{RASP}	60	125 000	70	125 000	ns	
$\overline{CAS}$ Pulse Width	t_{HCAS}	10	10 000	12	10 000	ns	
$\overline{CAS}$ Precharge Time	t_{CP}	10	–	10	–	ns	
Access Time from $\overline{CAS}$ Precharge	t_{ACP}	–	35	–	40	ns	
$\overline{CAS}$ Precharge to $\overline{WE}$ Delay Time	t_{CPWD}	52	–	59	–	ns	1
$\overline{RAS}$ Hold Time from $\overline{CAS}$ Precharge	t_{RHCP}	35	–	40	–	ns	
Read Modify Write Cycle Time	t_{HPRWC}	66	–	75	–	ns	
Data Output Hold Time	t_{DHC}	5	–	5	–	ns	
Output Buffer Turn-off Delay from $\overline{WE}$	t_{WEZ}	0	13	0	15	ns	2,3
$\overline{WE}$ Pulse Width	t_{WPZ}	10	–	10	–	ns	3
Output Buffer Turn-off Delay from $\overline{RAS}$	t_{OFR}	0	13	0	15	ns	2,3
Output Buffer Turn-off Delay from $\overline{CAS}$	t_{OFC}	0	13	0	15	ns	2,3

Notes 1. If $t_{WCS} \geq t_{WCS(MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geq t_{RWD(MIN.)}$, $t_{CWD} \geq t_{CWD(MIN.)}$, $t_{AWD} \geq t_{AWD(MIN.)}$, and $t_{CPWD} \geq t_{CPWD(MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

2. $t_{OFC(MAX.)}$, $t_{OFR(MAX.)}$ and $t_{WEZ(MAX.)}$ define the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL}.

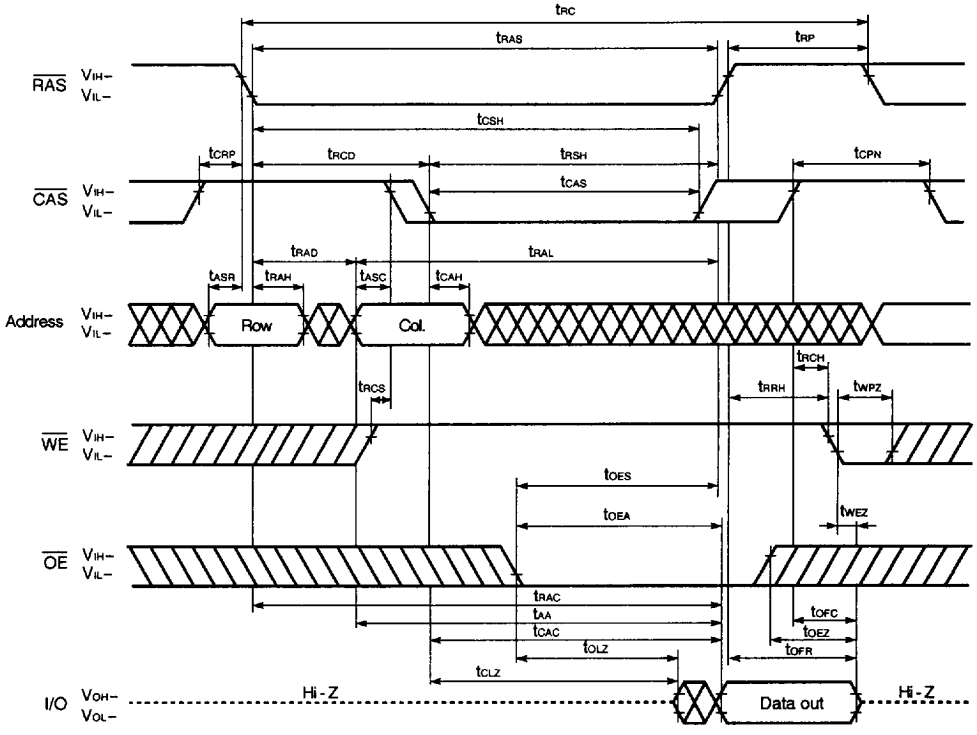
3. To make I/Os to Hi-Z in read cycle, it is necessary to control $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$ as follows. The effective specification depends on state of each signal.
   (1) $\overline{RAS}$, $\overline{CAS}$: inactive (at the end of read cycle)
   $\overline{WE}$: inactive, $\overline{OE}$: active
   t_{OFC} is effective when $\overline{RAS}$ is inactivated before $\overline{CAS}$ is inactivated.
   t_{OFR} is effective when $\overline{CAS}$ is inactivated before $\overline{RAS}$ is inactivated.
   (2) Both $\overline{RAS}$ and $\overline{CAS}$ are active or either $\overline{RAS}$ or $\overline{CAS}$ is active (in read cycle)
   $\overline{WE}$: active, $\overline{OE}$: active ··· t_{WEZ}, t_{WPZ} are effective.
   $\overline{WE}$: inactive, $\overline{OE}$: inactive ··· t_{OEZ} is effective.

Refresh Cycle

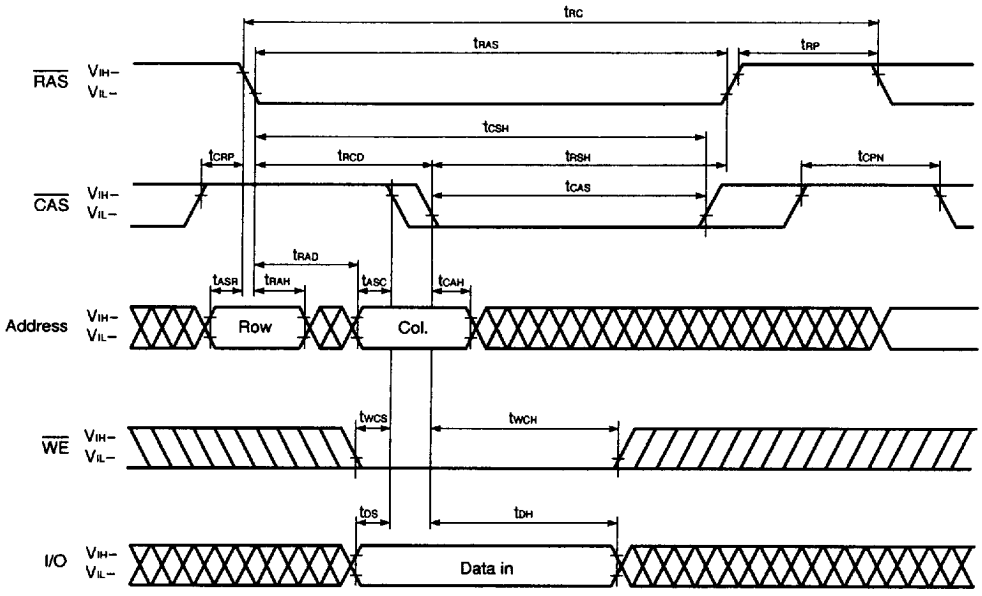
Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.		
$\overline{CAS}$ Setup Time	t_{CSR}	5	–	5	–	ns	
$\overline{CAS}$ Hold Time ($\overline{CAS}$ before $\overline{RAS}$ Refresh)	t_{CHR}	10	–	10	–	ns	
$\overline{RAS}$ Precharge $\overline{CAS}$ Hold Time	t_{RPC}	5	–	5	–	ns	
$\overline{RAS}$ Pulse Width ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)	t_{RASS}	100	–	100	–	μs	1
$\overline{RAS}$ Precharge Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)	t_{RPS}	110	–	130	–	ns	1
$\overline{CAS}$ Hold Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh)	t_{CHS}	-50	–	-50	–	ns	1
$\overline{WE}$ Setup Time	t_{WSR}	10	–	10	–	ns	
$\overline{WE}$ Hold Time (Hidden Refresh Cycle)	t_{WHR}	15	–	15	–	ns	

Note 1. This specification is applied only to the μPD42S16805L.

Read Cycle

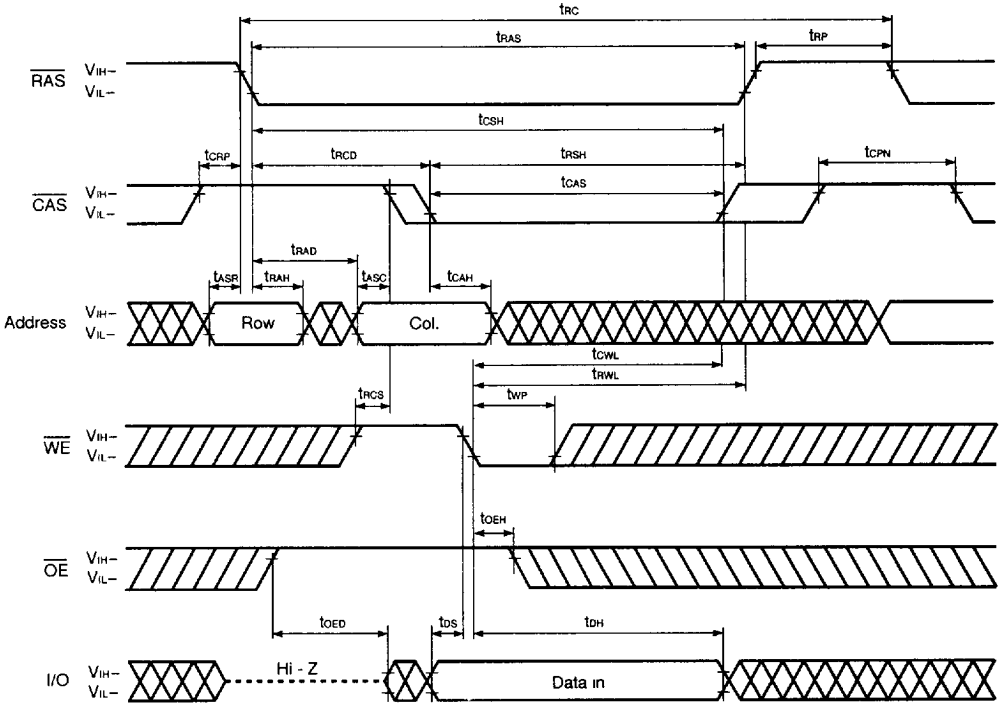


Early Write Cycle

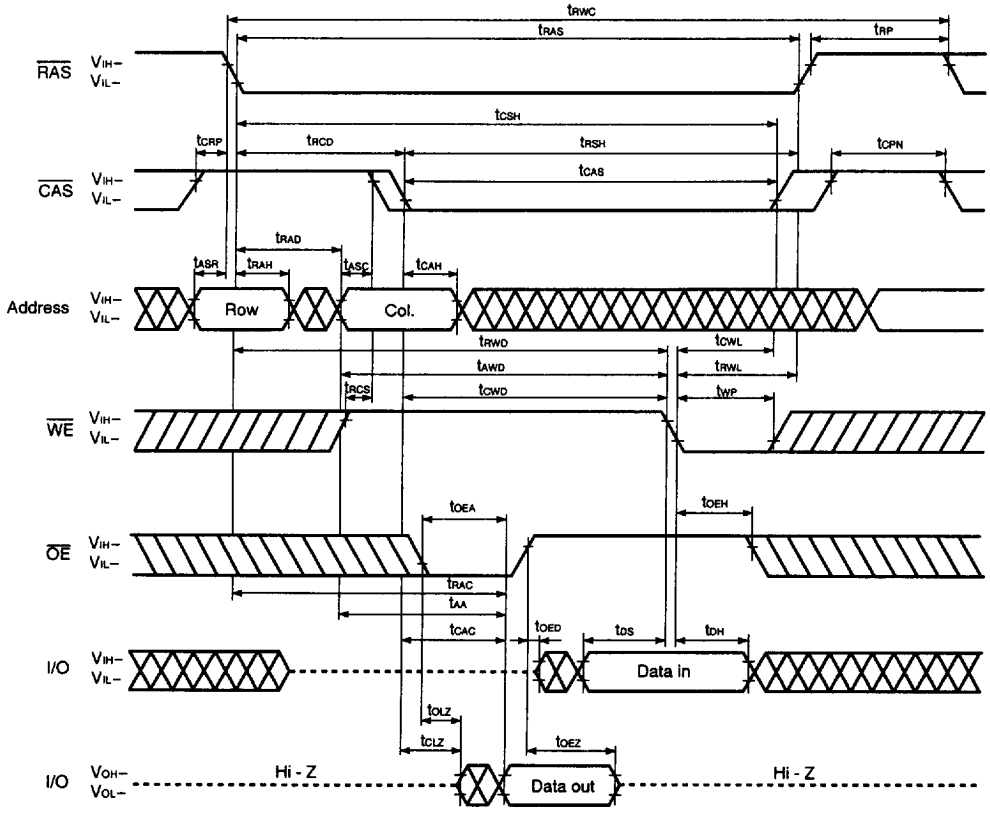


Remark $\overline{OE}$: Don't care

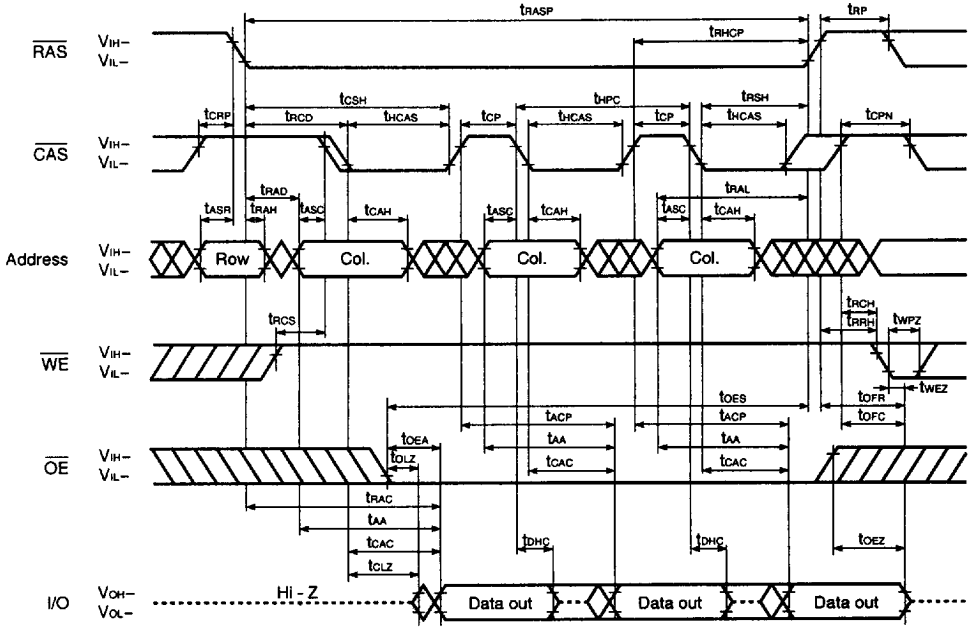
Late Write Cycle



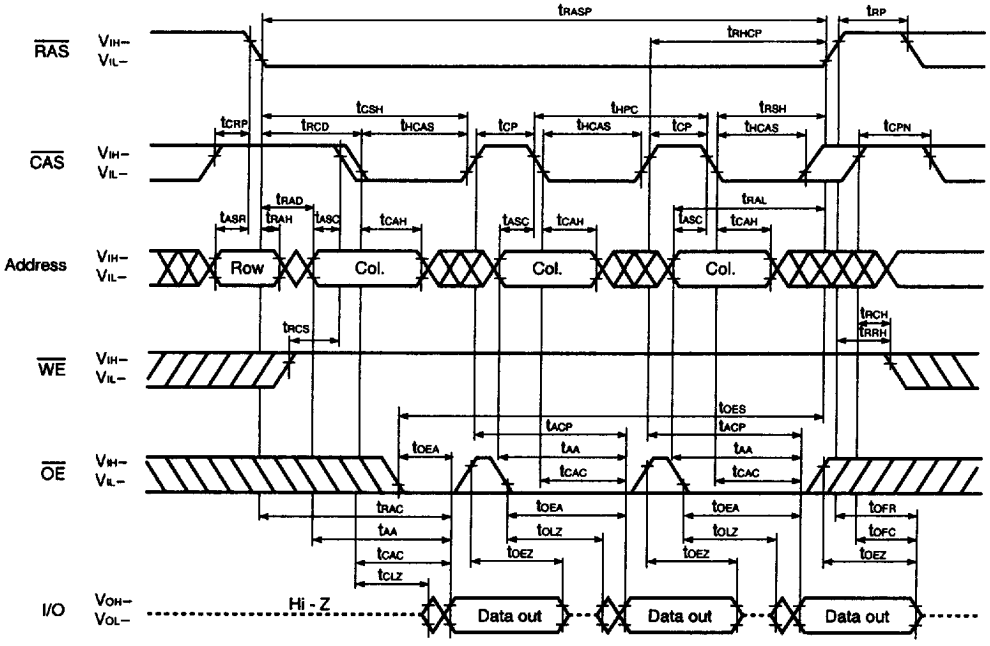
Read Modify Write Cycle



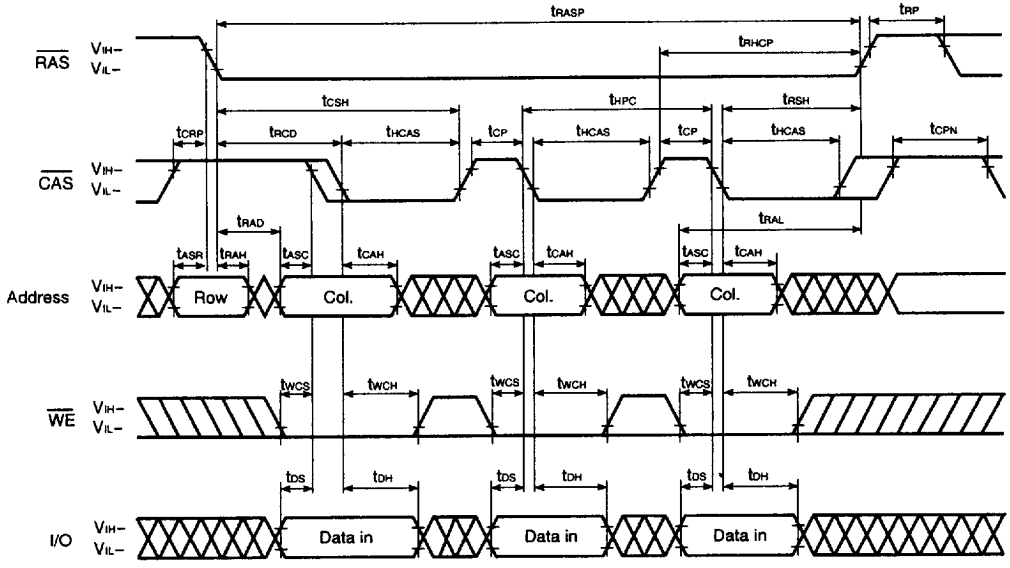
Hyper Page Mode Read Cycle



Hyper Page Mode Read Cycle ($\overline{OE}$ Control)

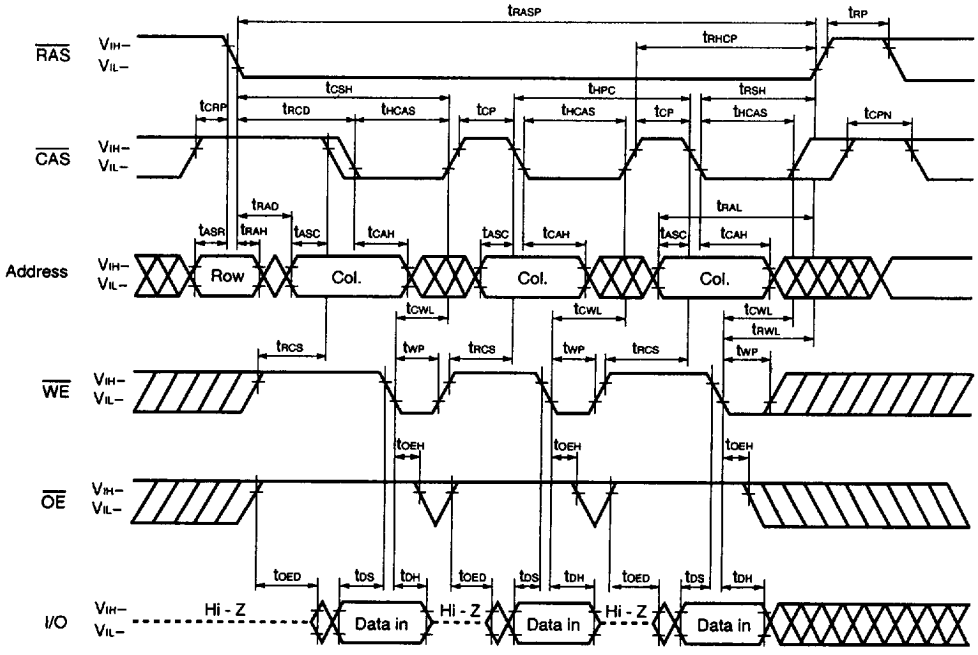


Hyper Page Mode Early Write Cycle

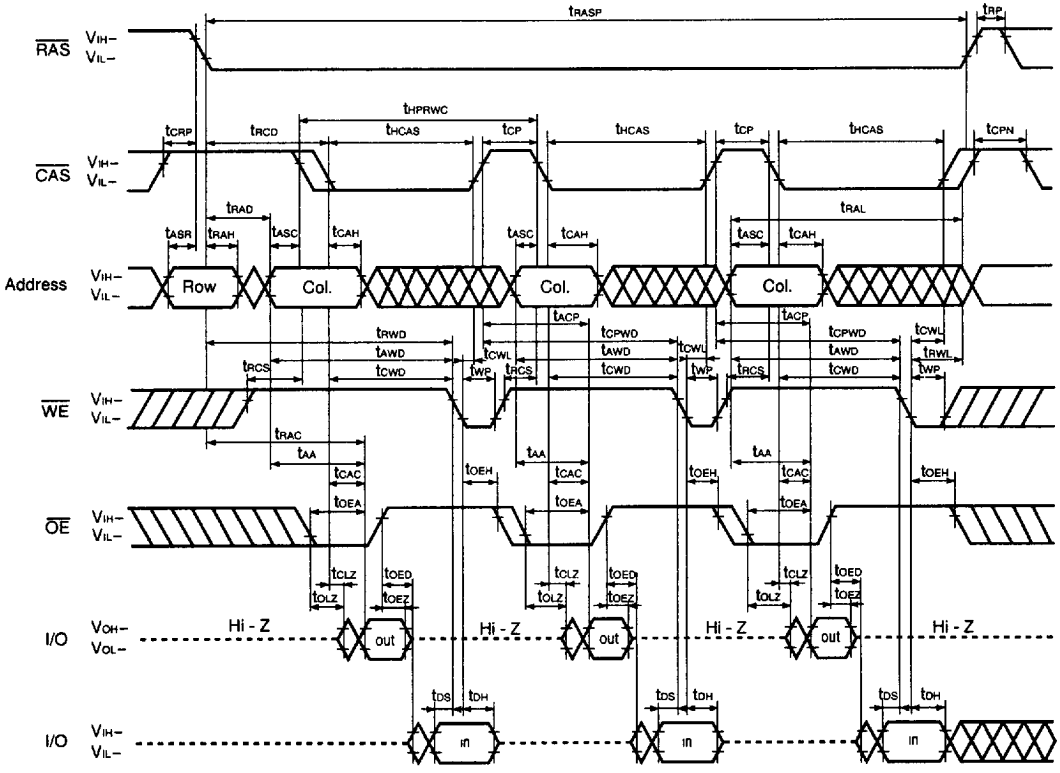


Remark $\overline{OE}$: Don't care

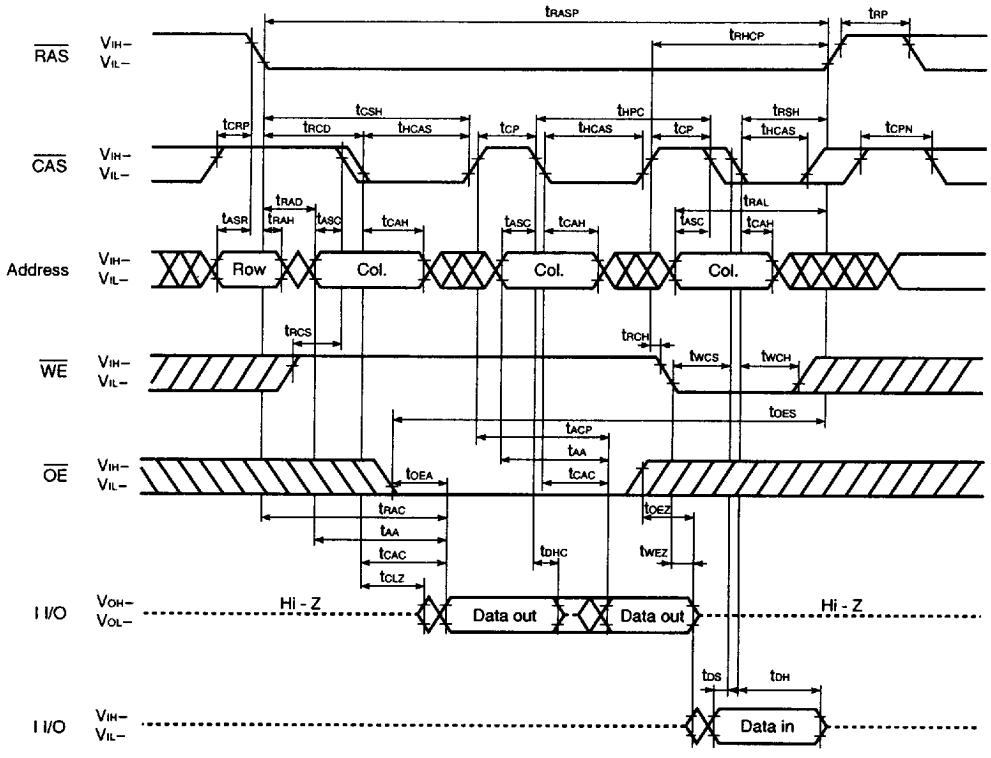
Hyper Page Mode Late Write Cycle



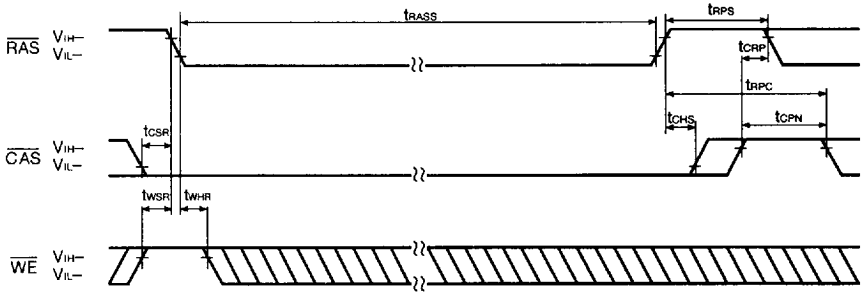
Hyper Page Mode Read Modify Write Cycle



Hyper Page Mode Read and Write Cycle



$\overline{CAS}$ Before $\overline{RAS}$ Self Refresh Cycle (Only for the μPD42S16805L)



Remark Address, $\overline{OE}$: Don't care I/O : Hi - Z

Cautions on Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh

$\overline{CAS}$ before $\overline{RAS}$ self refresh can be used independently when used in combination with distributed $\overline{CAS}$ before $\overline{RAS}$ long refresh; However, when used in combination with burst $\overline{CAS}$ before $\overline{RAS}$ long refresh or with burst long $\overline{RAS}$ only refresh, the following cautions must be observed.

(1) Normal Combined Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh and Burst $\overline{CAS}$ Before $\overline{RAS}$ Long Refresh

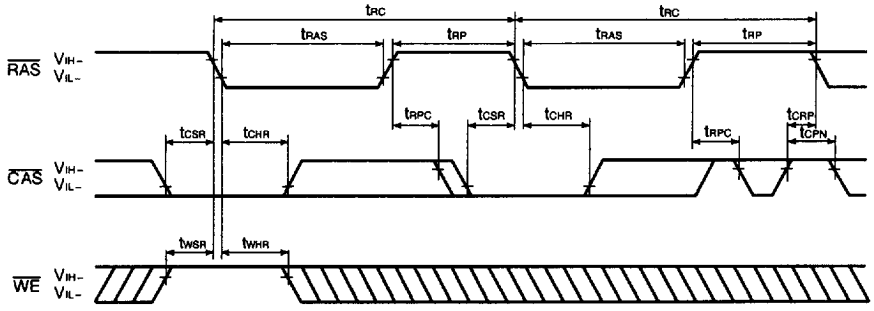
When $\overline{CAS}$ before $\overline{RAS}$ self refresh and burst $\overline{CAS}$ before $\overline{RAS}$ long refresh are used in combination, please perform $\overline{CAS}$ before $\overline{RAS}$ refresh 4 096 times within a 64 ms interval just before and after setting $\overline{CAS}$ before $\overline{RAS}$ self refresh.

(2) Normal Combined Use of $\overline{CAS}$ Before $\overline{RAS}$ Self Refresh and Burst Long $\overline{RAS}$ Only Refresh

When $\overline{CAS}$ before $\overline{RAS}$ self refresh and burst $\overline{RAS}$ only refresh are used in combination, please perform $\overline{RAS}$ only refresh 4 096 times within an interval of 64 ms or less just before and after setting $\overline{CAS}$ before $\overline{RAS}$ self refresh.

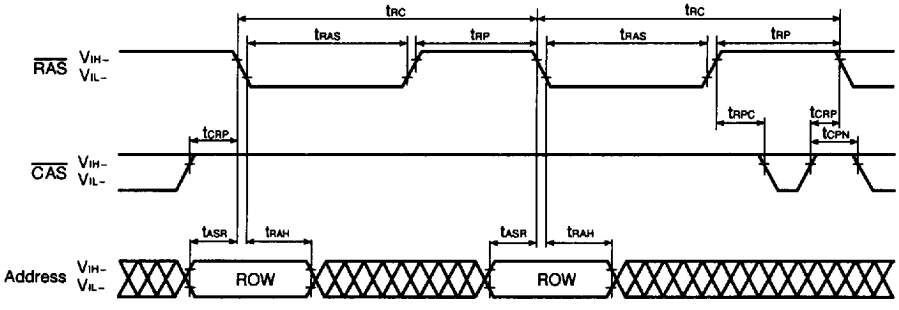
For details, please refer to **How to use DRAM** User's Manual.

$\overline{CAS}$ Before $\overline{RAS}$ Refresh Cycle



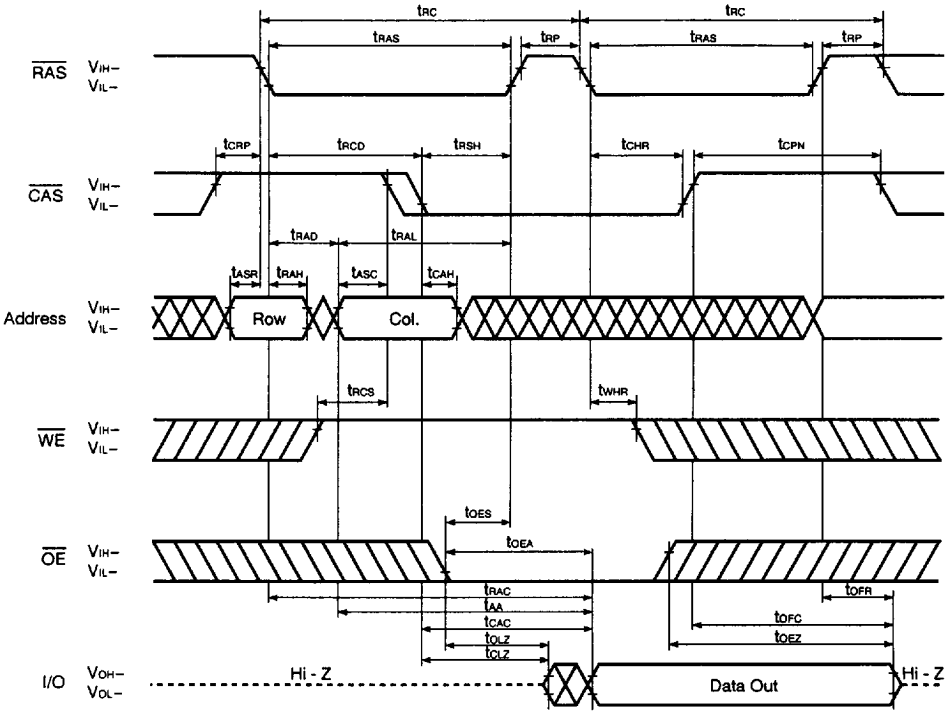
Remark Address, $\overline{OE}$ = Don't care I/O = Hi - Z

$\overline{RAS}$ Only Refresh Cycle

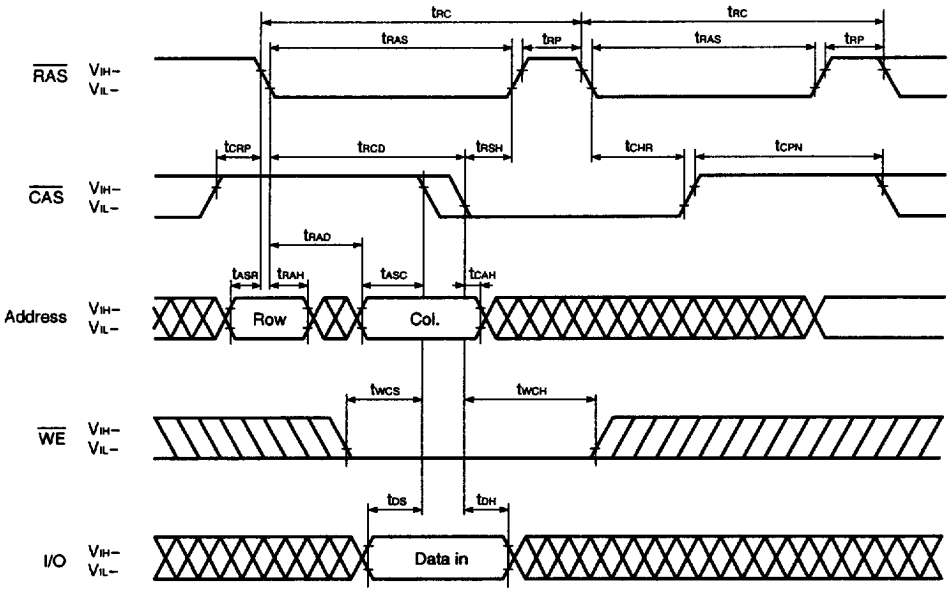


Remark $\overline{WE}$, $\overline{OE}$ = Don't care I/O = Hi - Z

Hidden Refresh Cycle (Read)

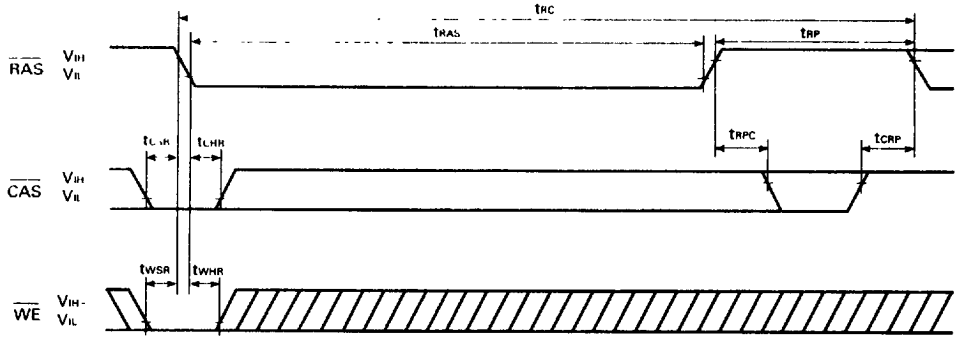


Hidden Refresh Cycle (Write)



Remark $\overline{OE}$: Don't care

Test Mode Set Cycle (WE, CAS Before RAS Refresh Cycle)



Remark Address, OE : Don't care I/O : HI - Z

Test Mode

By using the test mode, the test time can be reduced. The reason for this is that, the memory emulates the × 16-bit structure during test mode.

(1) Setting the mode

Executing the test mode cycle (WE, CAS before RAS refresh cycle) sets the test mode.

(2) Write/read operation

When either a "0" or a "1" is written to the input pin in test mode, this data is written to 16 bits of memory cell.

Next, when the data is read from the output pin at the same address, the cell can be checked.

Output="1" : Normal write (all memory cells)
Output="0" : Abnormal write

(3) Refresh

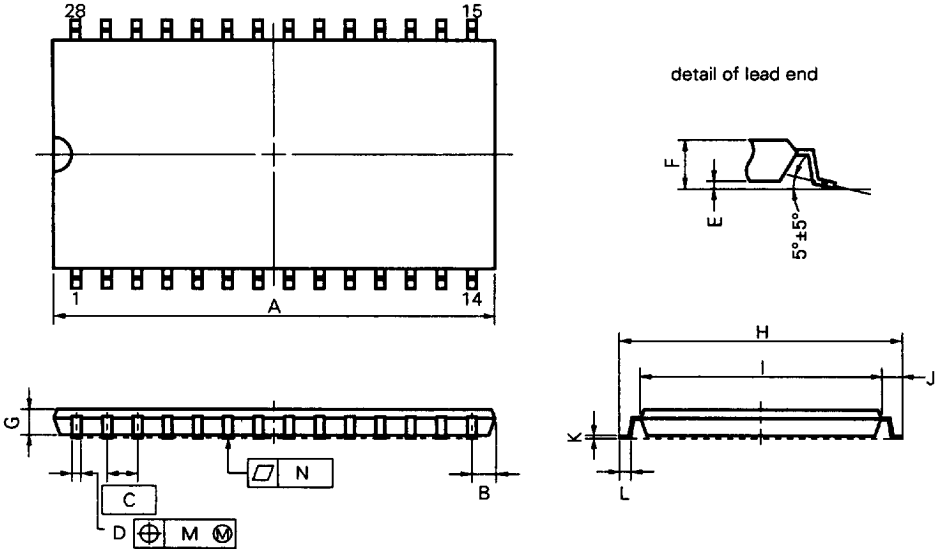
Refresh in the test mode must be performed with the RAS / CAS cycle or with the WE, CAS before RAS refresh cycle. The WE, CAS before RAS refresh cycle use the same counter as the CAS before RAS refresh's internal counter.

(4) Mode Cancellation

The test mode is cancelled by executing one cycle of RAS only refresh cycle or CAS before RAS refresh cycle.

Package Drawings

28 PIN PLASTIC TSOP(II) (400 mil)



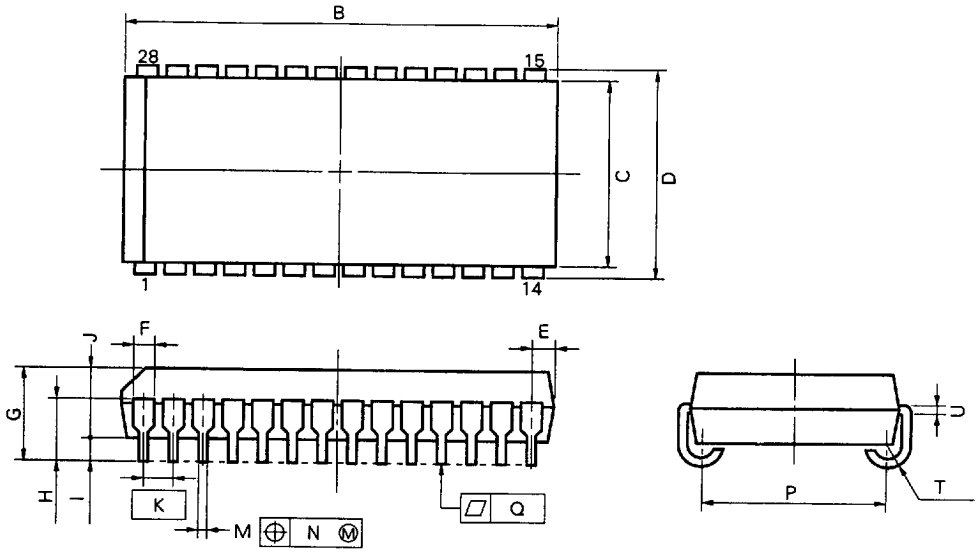
S28G5-50-7JD2-1

NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1 15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	$0.016^{+0.004}_{-0.005}$
E	0 05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	$0\ 031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5±0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC SOJ (400 mil)



P28LE-400A1

NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0.2}_{-0.35}$	$0.735^{+0.008}_{-0.013}$
C	10.16	0.400
D	11.18±0.2	$0.440^{+0.008}_{-0.007}$
E	1.08±0.15	$0.043^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5±0.2	$0.138^{+0.008}_{-0.007}$
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.40±0.20	$0.370^{+0.008}_{-0.007}$
Q	0.10	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μPD42S16805L, 4216805L.

Types of Surface Mount Device

μPD42S16805LG5-AXX, 4216805LG5-AXX : 28-pin Plastic TSOP (II) (400 mil)
μPD42S16805LLE-AXX, 4216805LLE-AXX : 28-pin Plastic SOJ (400 mil)